



GP
ELECTRONICS

GP3599KDW

30V N-Channel + P-Channel MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}TYP$	I_D
-30V	480mΩ@-10V	-0.45A
	690mΩ@-4.5V	
30V	290mΩ@10V	0.6A
	320mΩ@4.5V	

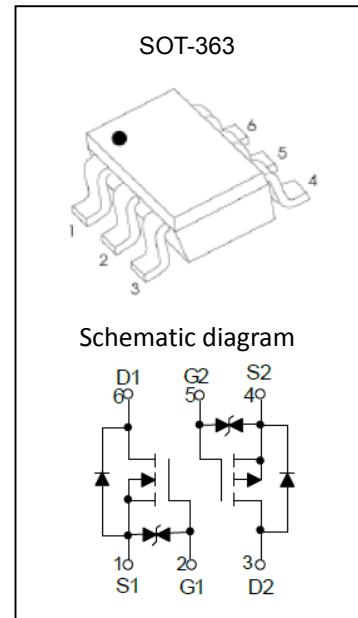
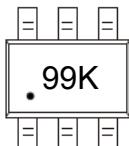
Feature

- Surface Mount Package
- Low $R_{DS(on)}$
- Low leakage current
- ESD Protected

Application

- Low voltage applications
- Load/Power Switching
- Battery Management for Ultra Small Portable Electronics

MARKING:



ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
P-MOSFET			
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ⁽¹⁾	I_D	-0.45	A
Pulsed Drain Current	I_{DM}	-1.2	A
Power Dissipation	P_D	1.4	W
N-MOSFET			
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	0.6	A
Pulsed Drain Current ⁽¹⁾	I_{DM}	2.2	A
Power Dissipation	P_D	1.4	W
Temperature and Thermal Resistance			
Thermal Resistance from Junction to Ambient ⁽²⁾	$R_{\theta JA}$	89	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55~+150	°C

P-channel MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-30			V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 10\text{V}, V_{\text{DS}} = 0\text{V}$			± 10	μA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-0.5	-1.0	-1.5	V
Drain-source on-resistance ⁽³⁾	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -0.30\text{A}$		480	620	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -0.30\text{A}$		690	900	
Forward transconductance	g_{FS}	$V_{\text{DS}} = -10\text{V}, I_D = -0.30\text{A}$		1.2		S
Dynamic characteristics⁽⁴⁾						
Input Capacitance	C_{iss}	$V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = 0\text{V}, F = 1.0\text{MHz}$		120		pF
Output Capacitance	C_{oss}			18		
Reverse Transfer Capacitance	C_{rss}			9		
Switching Characteristics⁽⁴⁾						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = -10\text{V}, I_D = -200\text{mA}, V_{\text{GS}} = -4.5\text{V}, R_G = 10\Omega$		9		nS
Turn-on rise time	t_r			6		
Turn-off delay time	$t_{\text{d}(\text{off})}$			34		
Turn-off fall time	t_f			20		
Source-Drain Diode characteristics						
Diode forward voltage	V_{DS}	$I_S = -0.4\text{A}, V_{\text{GS}} = 0\text{V}$			-1.2	V

N-channel MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	30			V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 10\text{V}, V_{\text{DS}} = 0\text{V}$			± 3	μA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250\mu\text{A}$	0.5	1.0	1.5	V
Drain-source on-resistance ⁽³⁾	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 0.6\text{A}$		290	370	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_{\text{D}} = 0.6\text{A}$		320	500	
Forward transconductance	g_{FS}	$V_{\text{DS}} = 5\text{V}, I_{\text{D}} = 0.5\text{A}$		0.9		S
Dynamic characteristics⁽⁴⁾						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 0\text{V}, F = 1.0\text{MHz}$		44		pF
Output Capacitance	C_{oss}			15		
Reverse Transfer Capacitance	C_{rss}			8		
Switching Characteristics⁽⁴⁾						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 10\text{V}, I_{\text{D}} = 0.7\text{A}$ $V_{\text{GS}} = 4.5\text{V}, R_{\text{GEN}} = 51\Omega$		5		ns
Turn-on rise time	t_{r}			8		
Turn-off delay time	$t_{\text{d}(\text{off})}$			23		
Turn-off fall time	t_{f}			41		
Source-Drain Diode characteristics						
Diode forward voltage	V_{DS}	$I_{\text{S}} = 0.6\text{A}, V_{\text{GS}} = 0\text{V}$		0.87	1.2	V

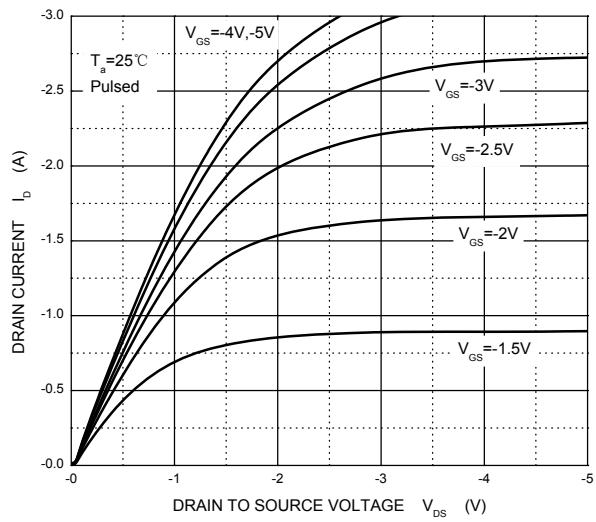
Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t < 5$ sec.
3. Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing.

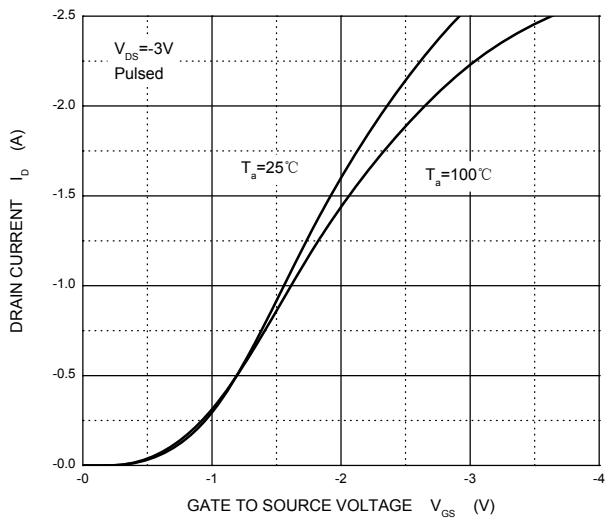
Typical Electrical and Thermal Characteristics

P-Channel MOS

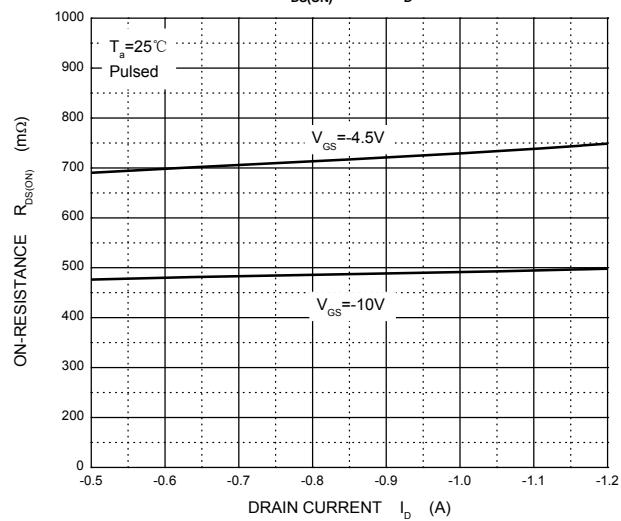
Output Characteristics



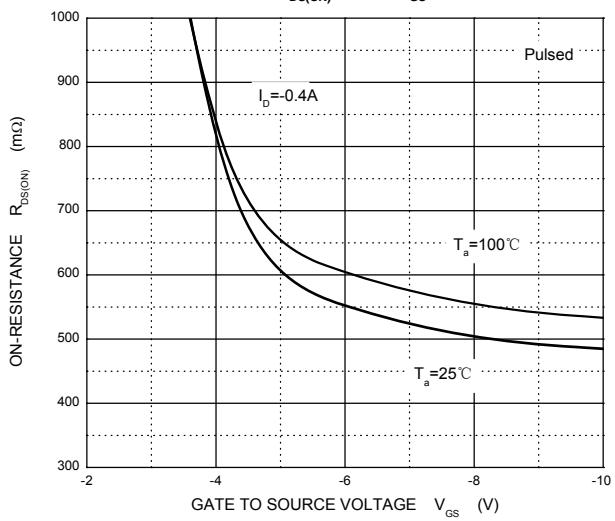
Transfer Characteristics



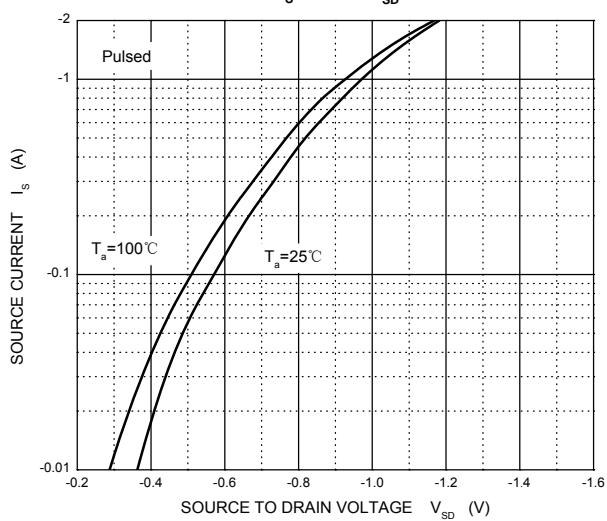
$R_{DS(ON)}$ — I_D



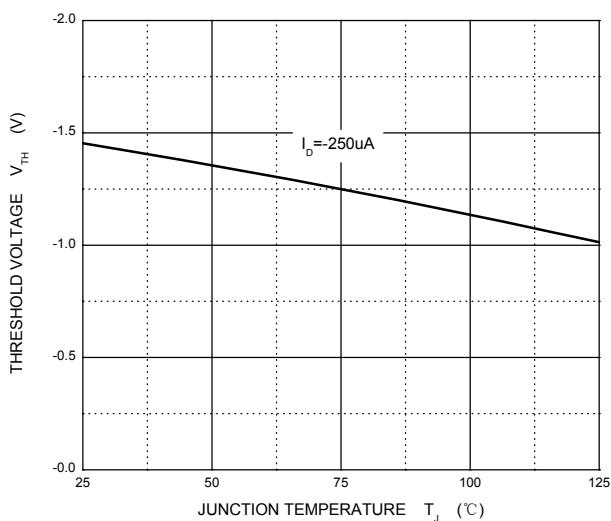
$R_{DS(ON)}$ — V_{GS}

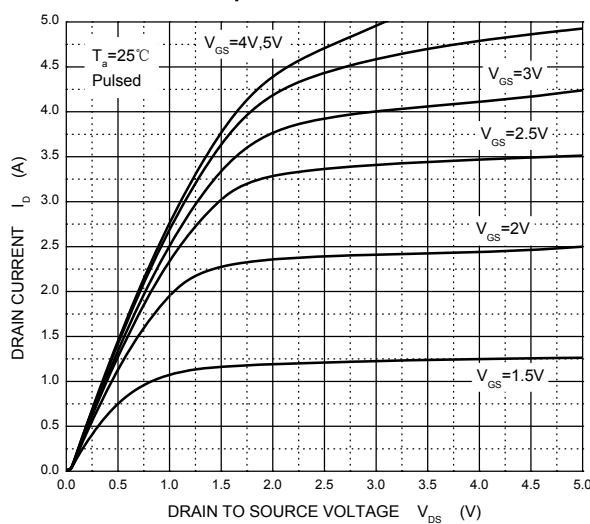
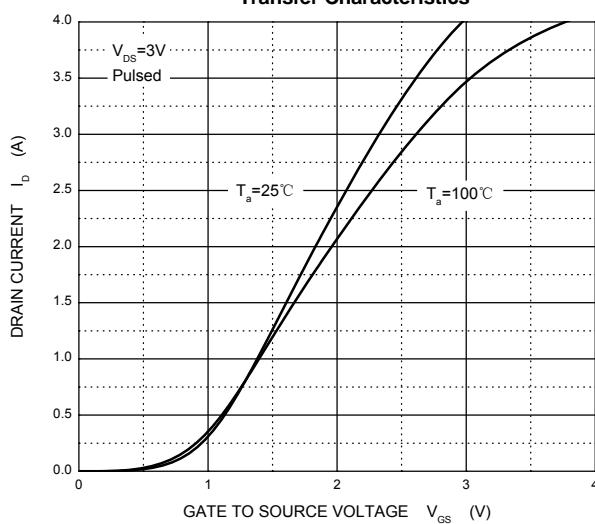
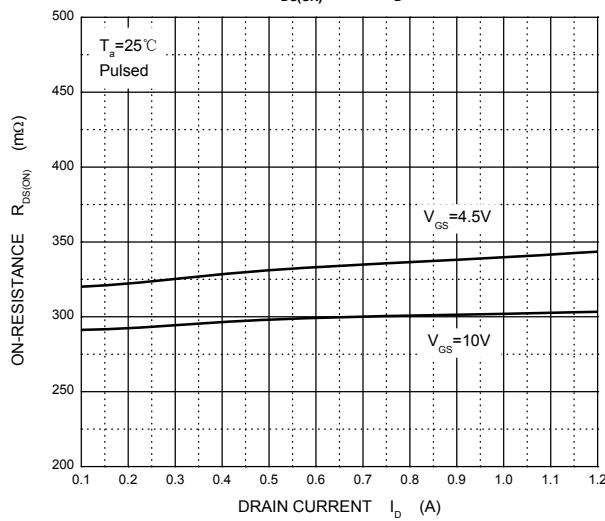
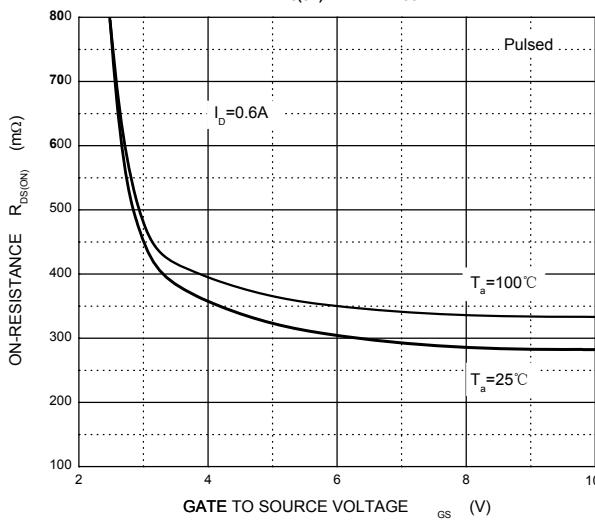
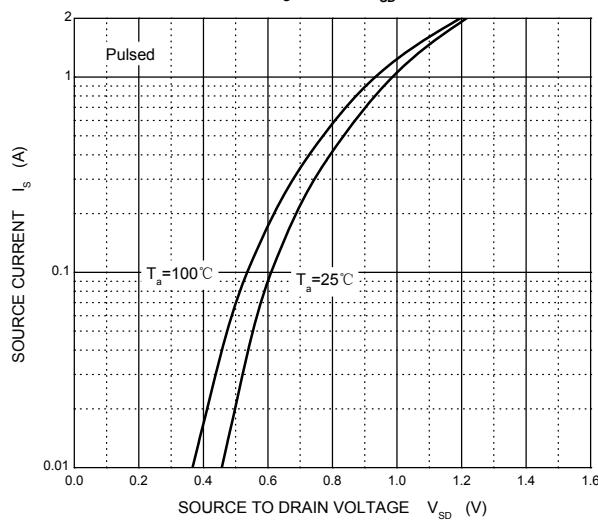
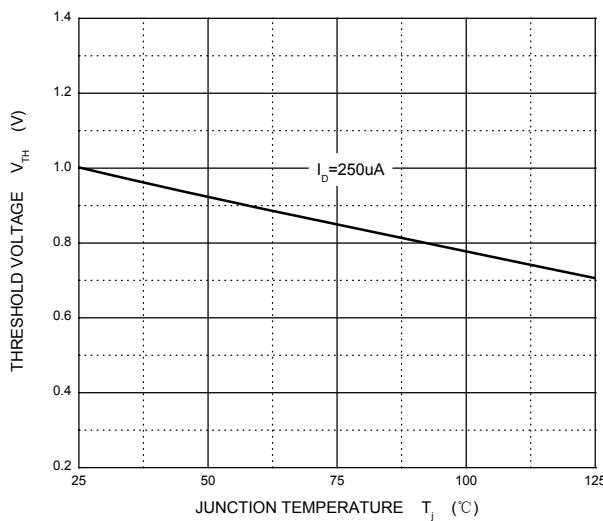


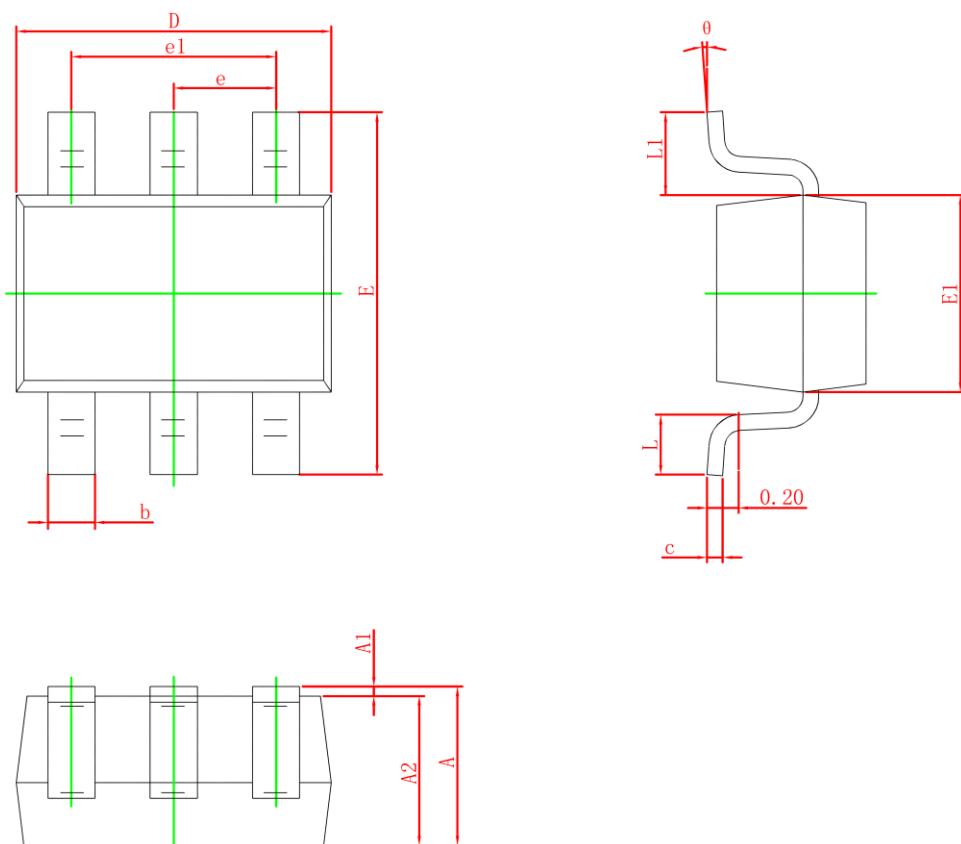
I_s — V_{SD}



Threshold Voltage



N-Channel MOS
Output Characteristics

Transfer Characteristics

 $R_{DS(ON)}$ — I_D

 $R_{DS(ON)}$ — V_{GS}

 I_S — V_{SD}

Threshold Voltage


SOT-363 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A1	0	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.080	0.150	0.003	0.006
D	1.800	2.200	0.071	0.087
E	2.000	2.450	0.079	0.096
E1	1.150	1.350	0.045	0.053
e	0.650TYP		0.026TYP	
e1	1.200	1.400	0.047	0.055
L1	0.525REF		0.021REF	
L	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°